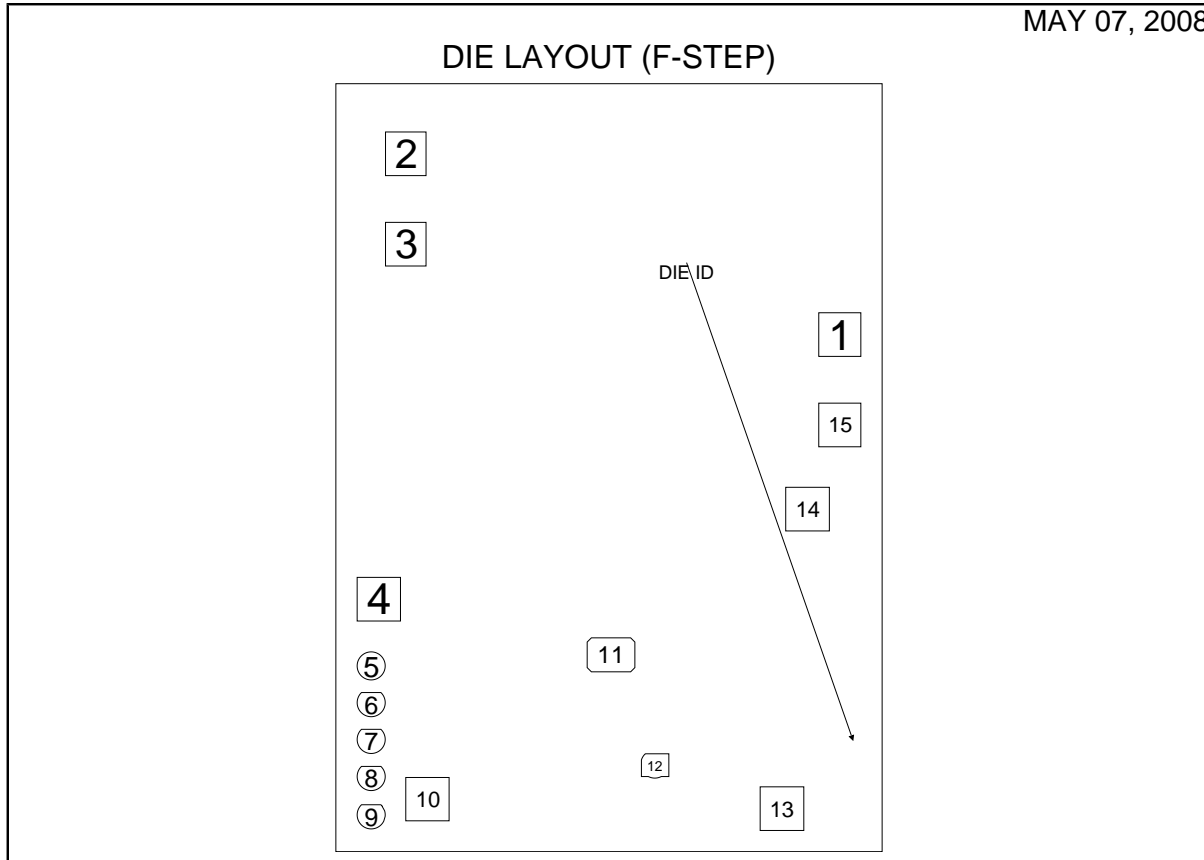


LM2941 MD8 MW8
1A LOW DROPOUT ADJUSTABLE REGULATOR

MAY 07, 2008



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1940F	Bond Pad Opening Size (min)	130.00µm x 140.00µm
Die Step	F	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDON NITRIDE
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1752.6µm x 2463.8µm 69.0mils x 97.0mils	Back Side Connection	GND
Thickness	304.8µm Nominal		
Min Pitch	118µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(F-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
VIN	1	740	427	135	x	140
OUTPUT	2	-652	1007	130	x	140
OUTPUT	3	-652	717	130	x	140
GND	4	-738	-422	139	x	140
NC	5	-763	-636	90	x	89
NC	6	-762	-760	89	x	77
NC	7	-762	-878	89	x	77
NC	8	-762	-997	89	x	77
NC	9	-762	-1120	89	x	77
ADJ	10	-582	-1063	139	x	139
NC	11	6	-600	153	x	109
NC	12	148	-957	88	x	78
ON/OFF	13	555	-1094	140	x	140
GND	14	637	-133	140	x	140
VIN	15	740	137	135	x	140

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